

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

LISTING OF CLAIMS:

1. (canceled)
2. (currently amended) ~~The apparatus according to claim 1,~~ A wafer polishing apparatus comprising:
 - an abrasive pad;
 - a platen for holding and rotating said abrasive pad;
 - a head for holding a wafer and rotating the wafer while pressing the wafer against the abrasive pad; and
 - conditioning mechanism for honing the abrasive pad including
 - a conditioner for honing the pad in contact therewith,
 - a conditioner driving unit for holding and rotating the conditioner,
 - an arm for holding the conditioner driving unit, and
 - a plurality of detectors each detecting a force in the rotational direction of the platen and a force in the radial direction orthogonal to the rotational direction of the platen among forces applied to the conditioner driving unit,

wherein said detectors each includes a rotational directional pressure detector located between one side along the

rotational direction of the platen, of the conditioner driving unit and the holding portion of the arm, and two radial directional pressure detectors located between the both sides along the radial direction of the platen, of the conditioner driving unit and the holding portion of the arm, and

a fixing jig for holding the conditioner driving unit is provided between the other side along the rotational direction of the platen, of the conditioner driving unit and the holding portion of the arm.

3. (original) The apparatus according to claim 2, wherein

the holding portion of said arm is a hole into which the conditioner driving unit is inserted, and

said conditioner driving unit is held in the hole through the rotational directional pressure detector, the two radial directional pressure detectors, and the fixing jig.

4. (canceled)

5. (canceled)

6. (original) The apparatus according to claim 2, further comprising a memory for storing correlations between output values of said detectors and polishing quantities of said

wafer.

7. (original) The apparatus according to claim 3, further comprising a memory for storing correlations between output values of said detectors and polishing quantities of said wafer.

8. (canceled)

9. (canceled)

10. (original) The apparatus according to claim 2, further comprising a controller which determines whether detection values of said detectors are within acceptable limits and when any one of the values is out of the limits, changing conditioning terms.

11. (original) The apparatus according to claim 3, further comprising a controller which determines whether detection values of said detectors are within acceptable limits and when any one of the values is out of the limits, changing conditioning terms.

12. (canceled)

13. (canceled)

14. (original) The apparatus according to claim 6, further comprising a controller which determines whether detection values of said detectors are within acceptable limits and when any one of the values is out of the limits, changing conditioning terms.

15. (original) The apparatus according to claim 7, further comprising a controller which determines whether detection values of said detectors are within acceptable limits and when any one of the values is out of the limits, changing conditioning terms.

16. (canceled)

17. (canceled)